

Due Date August 19, 2006

OSMM&N File No. 288839US0PCT

By NFO/atw/FF

Serial No. New U.S. PCT Application based on PCT/EP04/53669

In the matter of the Application of Ekkehard MUEH, et al.

For SILICON COMPOUNDS FOR PRODUCING SiO<sub>2</sub>-CONTAINING  
INSULATING LAYERS ON CHIPS

The following has been received in the U.S. Patent Office on the date stamped hereon:

■ Combined Declaration, Petition & Power of Attorney (4 pages)

■ Application Data Sheet (3 pages)

■ Notice of Priority

■ Dep. Acct. Order Form

■ Credit Card Payment Form for \$1,000.00

■ PCT Transmittal Letter

■ Preliminary Amendment

■ PCT/IB/304

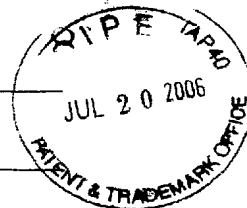
■ Information Disclosure Statement

■ PTO-1449

■ List of Related Cases

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